Final Product/Process Change Notification

Document #:FPCN27334Z
Issue Date: 29 Jul 2026

Title of Change:	Adjustment of Wafer Thickness for SC70 PIN Package for PIN Diode Devices at onsemi ISMF Fab (Malaysia)
Proposed Changed Material First Ship Date:	05 Feb 2027 or earlier if approved by customer
Current Material Last Order Date:	N/A *Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability*.
Current Material Last Delivery Date:	N/A *The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory*
Product Category:	Active components – Discrete components
Contact information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	15 July 2026
PPAP Availability Date:	15 August 2026
Additional Reliability Data:	Contact your local onsemi Sales Office
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com

Change Category

Category	Type of Change
Process - Wafer Production	SEM-PW-03: New final wafer thickness

Description and Purpose:

onsemi wishes to inform customers of a wafer thickness adjustment for SC70-package PIN diode devices manufactured at onsemi ISMF Fab (Malaysia).

The wafer thickness will be updated from 4 mil to 6 mil to align with the correct wafer thickness specification.

SC70 package

	From	To
Wafer Thickness	4 mil	6 mil

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Reason / Motivation for Change:	Process/Materials Change
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi, ISMF Malaysia	None

Marking of Parts/ Traceability of Change:	Changed material can be identified through assembly plant code and lot code which follow onsemi marking format.

Reliability Data Summary:

QV DEVICE NAME : NSVP249SDSF3T1G
RMS : 108669
PACKAGE : SC70

Test	Specification	Condition	Interval	Results
Preconditioning	J-STD-020 JESD-A113	MSL 1 @260°C	-	0/100
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2min	15,000 cyc	0/80
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/100

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

Current Part Number	New Part Number	Qualification Vehicle
NSVP264SDSF3T1G	#NONE	NSVP249SDSF3T1G
NSVP249SDSF3T1G	#NONE	NSVP249SDSF3T1G